



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
* : Required Field			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-09-02
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Laurent TOSI	Representative Title	MMS MD CHAMPION
Representative Phone *	33 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement


Supplier Acceptance *	true	Legal Declaration *	Standard
------------------------------	-------------	----------------------------	-----------------

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
M24C08-WMN6TP	PX07*24081TA	A	9998	2014-06-17
Amount		UoM	Unit type	ST ECOPACK Grade
80.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



 life.augmented

Package Designator	Size	Nbr of instances	Shape	
SON	JEDEC	8	L bend	
Comment	Package: 07 SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	PXO7*24081TA					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	0.203	mg	supplier	die	Silicon (Si)	7440-21-3		0.195	mg	960591	2438
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.001	mg	4926	13
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.001	mg	4926	13
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.006	mg	29557	75
LEADFRAME	Other inorganic materials	51.527	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		49.798	mg	966445	622475
LEADFRAME				supplier	ALLOY	Iron (Fe)	7439-89-6		1.200	mg	23289	15000
LEADFRAME				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.062	mg	1203	775
LEADFRAME				supplier	ALLOY	Phosphorus (P)	7723-14-0		0.015	mg	291	188
LEADFRAME				supplier	COATING	Nickel (Ni)	7440-02-0		0.439	mg	8520	5488
LEADFRAME				supplier	COATING	Palladium (Pd)	7440-05-3		0.009	mg	175	113
LEADFRAME				supplier	COATING	Gold (Au)	7440-57-5		0.004	mg	78	50
DIE ATTACH	Other inorganic materials	0.173	mg	supplier	GLUE	Epoxy resin A	9003-36-5		0.012	mg	69364	150
DIE ATTACH				supplier	GLUE	Epoxy resin B	68475-94-5		0.007	mg	40462	88
DIE ATTACH				supplier	GLUE	Silver(Ag)	7440-22-4		0.133	mg	768786	1663
DIE ATTACH				supplier	GLUE	Lactone	96-48-0		0.007	mg	40462	88
DIE ATTACH				supplier	GLUE	Polyoxypropylenediamine	9046-10-0		0.007	mg	40462	88
DIE ATTACH				supplier	GLUE	2,6-Diglycidyl phenyl allyl ether oligomer	Trade secret		0.007	mg	40462	88
BONDING WIRE	Other inorganic materials	0.099	mg	supplier	BONDING WIRE	Copper (Cu)	7440-50-8		0.097	mg	979798	1213
BONDING WIRE				supplier	BONDING WIRE	Palladium (Pd)	7440-05-3		0.002	mg	20202	25
ENCAPSULATION	Other inorganic materials	27.808	mg	supplier	MOLDING COMPOUND	Epoxy Resin	Trade secret		3.198	mg	115003	39975
ENCAPSULATION				supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		24.471	mg	879999	305888
ENCAPSULATION				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		0.139	mg	4999	1738
FINISHING	Other inorganic materials	0.190	mg	supplier	CONNECTION COATING	Nickel (Ni)	7440-02-0		0.185	mg	973684	2313
FINISHING				supplier	CONNECTION COATING	Palladium (Pd)	7440-05-3		0.004	mg	21053	50
FINISHING				supplier	CONNECTION COATING	Gold (Au)	7440-57-5		0.001	mg	5263	13